PCN Number:	20200803000.1	PCN Date:	Aug 03, 2020
Title:	PBO to PI conversion for the OPA2211AIDDA/R device		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Nov 03, 2020	Estimated Sample Availability:	Date provided at sample request

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

This notification is to announce the qualification of Polyimide as a replacement for the current PBO die coat for the OPA2211AIDDA/R device.

	Current	Proposed
Passivation	PBO	PI
Leadframe	NiPdAu (Non-rough)	NiPdAu (Single Side Top Roughened)

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp

Changes to product identification resulting from this PCN:

None

Product Affected:

OPA2211AIDDA	OPA2211AIDDAR

Qualification Data

Approved on 07/29/2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: OPA2211AIDDA	QBS Process Reference: INA826AIDGK	QBS Process Reference: OPA1612AID	QBS Process Reference: OPA209AID	QBS Process Reference: OPA827AIDGK
HTOL	Life Test, 150C	300 Hours	-	1/77/0	3/231/0	1/77/0	1/74/0
HBM	ESD - HBM	2500 V	-	1/3/0	1/3/0	1/3/0	1/3/0
CDM	ESD - CDM	1000 V	-	1/3/0	1/3/0	1/3/0	1/3/0
LU	Latch-up	Per JESD78	-	1/12/0	2/12/0	1/12/0	1/6/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	3/90/0	1/30/0	1/30/0
-	Pb Free Solderability	Pb Free/Solderability	3/66/0	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	3/90/0	1/30/0	1/30/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	1/45/0	3/135/0	1/45/0	1/45/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	1/77/0	3/231/0	1/77/0	1/77/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	-	-	-

- QBS: Qual By Similarity
- Qual Device OPA2211AIDDA is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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